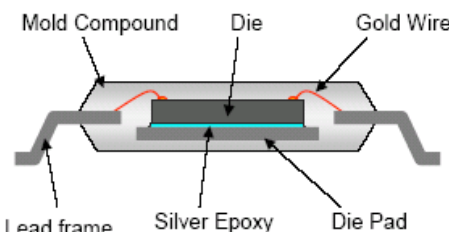


Material Declaration

Compliance Date: Feb./24/2022

RoHS Compliance: Yes

MSL: 3

Pin count /Package		44L 400mil TSOPII								
Model (Part) Number		AS6C1608B-45TIN								
Package Weight (mg)		436.50								
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part	
Chip	Wafer Circuit	13.79	3.16	31,592	Silicon (Si)	7440-21-3	13.790	3.159%	100.00%	
Bonding Wire	Conductivity	0.86	0.20	1,970	Gold (Au)	7440-57-5	0.860	0.197%	100.00%	
Die Attach	Conductivity	1.09	0.25	2,497	Silver (metal powder)	7440-22-4	0.839	0.192%	77.00%	
					Acrylic resin	(Trade secret)	0.093	0.021%	8.50%	
					Polybutadiene derivative	(Trade secret)	0.060	0.014%	5.50%	
					Butadiene copolymer	(Trade secret)	0.011	0.002%	1.00%	
					Epoxy resin	(Trade secret)	0.027	0.006%	2.50%	
					Acrylate	(Trade secret)	0.044	0.010%	4.00%	
					Peroxide	(Trade secret)	0.005	0.001%	0.50%	
					Additive	(Trade secret)	0.011	0.002%	1.00%	
Lead Frame	Base Metal	177.01	40.55	405,521	Iron (Fe)	7439-89-6	97.364	22.306%	55.01%	
					Nickel (Ni)	7440-02-0	71.742	16.436%	40.53%	
					Manganese(Mn)	7439-96-5	1.196	0.274%	0.68%	
					Silicon (Si)	7440-21-3	0.427	0.098%	0.24%	
					Carbon (C)	7440-44-0	0.085	0.020%	0.05%	
					Silver (Ag)	7440-22-4	6.195	1.419%	3.50%	
Molding Compound	Chip Protection	234.2	53.65	536,541	Silica (SiO ₂)	60676-86-0	208.438	47.752%	89.00%	
					Epoxy Resin (1)	(Trade secret)	7.026	1.610%	3.00%	
					Epoxy Resin (2)	(Trade secret)	4.684	1.073%	2.00%	
					Phenol Resin (1)	(Trade secret)	4.684	1.073%	2.00%	
					Phenol Resin (2)	(Trade secret)	4.684	1.073%	2.00%	
					Carbon Black (C)	1333-86-4	0.703	0.161%	0.30%	
					Others	(Trade secret)	3.981	0.912%	1.70%	
Plating of lead frame	Solder Plating	9.55	2.19	21,879	Tin (Sn)	53408-94-9	9.550	2.188%	100.00%	